

Q1,Q2,Q3,Q4 INSTALLATION FOR OPT.

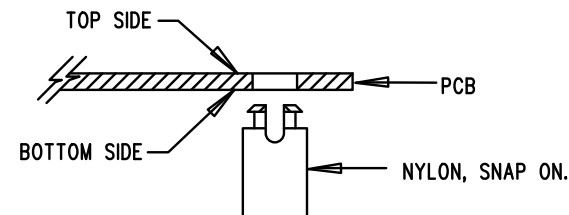


REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	4	PRODUCTION	VICTOR K.	01-05-18

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



APPROVALS

PCB DES.	LT
APP ENG.	VICTOR K.
SCALE = NONE	

ANALOG DEVICES POWER BY LINEAR™ www.linear.com FOR ADI CUSTOMER USE ONLY		
TITLE: TOP ASSEMBLY DRAWING		
DUAL OUTPUT SEPIC AND BUCK CONVERTER		
SIZE N/A	IC NO. LTC3892EUH-2 DEMO CIRCUIT 2727A	REV. 4
FILENAME: DC2727A-4.PCB		SHT 1 OF 2